IPC ASSOCIATION CONNELECTRONICS INDU	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ials and Mfc Information				
upplier Inf	formation	,							,						
Company name*			Company unique ID			J	Unique ID Authority					Response Date*			
nsemi											2024-05-04				
Contact Name		Title - Contact			I	Phone - Contact*				Email - Contact*					
Product-Env-S	Stewards		Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com				
uthorized Rej	epresentative*	Title - Representative			I	Phone - Representative*				Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com				
Req	quester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Version	N	Manufacturing Site		eight*	UOM	Unit Type	
		FOD8343TR2V 4A WIDE LEAD		4A WIDE LEAD G	GATE DRIVER	R	2024-05-04 LITEONFO		ITEONFG	20	3.109	mg	Each		
	ring Process Informa		Carminal Daga	Alloy	STD-020 MSL	Dating	Dools Droo	oss Pady T	mparatur	May Time at Peak	Tomporotus	a Numb	er of Reflow Cyc	las	
2 2			Terminal Base Alloy J-STD-020 MS CU Alloy 1		S1D-020 MSL	. Kanng	Peak Process Body Temperat		T .				er of Reflow Cyc	ies	
•	tte 11n (Sn) - annealed	C	U Alloy	I			200		IC	30	seconds	3			
omments			Ji :. 10 1	20 1-											
	num time at peak temperat	8													
r more infor	rmation regarding materia	I composition	piease refer t	o page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Coupling Gel	0.37	mg	Supplier	Filler (SiO2)	68909-20-6		0.074	mg
			Supplier	Dimethyl Siloxane	68083-19-2		0.296	mg
Die	0.099	mg	В	Gallium Arsenide (AsGa)	1303-00-0		0.033	mg
			Supplier	Silicon (Si)	7440-21-3		0.066	mg
Die Attach	0.092	mg	Supplier	Silver (Ag)	7440-22-4		0.0754	mg
			Supplier	Dicyandiamine	461-58-5		0.0009	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.0156	mg
Lead Frame	35.26	mg	Supplier	Silver (Ag)	7440-22-4		0.1763	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0317	mg
			Supplier	Iron (Fe)	7439-89-6		0.7405	mg
			Supplier	Copper (Cu)	7440-50-8		34.2798	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0317	mg
Mold Compound-Black	125.09	mg	В	Brominated Bisphenol A Diglycidyl Ether	r 40039-93-8		2.5018	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		1.8763	mg
			Supplier	Carbon Black (C)	1333-86-4		0.6254	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		88.8139	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		21.8907	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		9.3818	mg
Mold Compound-White	39.44	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		7.888	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		27.608	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		3.944	mg
Plating	0.36	mg	Supplier	Tin (Sn)	7440-31-5		0.36	mg
Wire Bond - Au	2.398	mg	Supplier	Gold (Au)	7440-57-5		2.398	mg